



Scholarship Application

Date:

Name:

Current Address:

Telephone:

Home Address

Home Telephone:

Email:

Name and Address of University to enroll in this fall:

Enrolling as Junior, Senior, or Graduate?

Current Level: Sophomore, Junior, or Graduate

Major:

GPA Last Semester: Cumulative GPA:

Means of financing Education, by percentage:

Parents:

Earnings:

Loans:

Additional information regarding financial needs:

Academic awards and honors:

Work Experience of recent years:

College Activities:

Plans or aspirations for employment or activity following graduation:

Please attach an essay of 500 to 1000 words: Why are you interested in agriculture, particularly as it relates to the U.S. Seed Industry? Note: not a personal history.

Submission of this form signifies the release of the above information for reviews by persons screening for scholarships.

Your official college transcript, mailed to us by your college, is necessary for you to qualify for consideration.

Please submit your application by 15 January 2009.

Scholarship winners will be notified following the annual meeting of the Pacific Seed Association on 15 February 2009.

Send your application to:

Stu Barclay
Summit Seed Coatings
P.O. Box E
Caldwell, Idaho 83606
stu_summit@qwestoffice.net